ABSTRACT

Provided is a semiconductor element-forming composition used in forming circuits of semiconductor devices and the like, the semiconductor element-forming composition satisfying all of good coatability, film-curability in a short period of time, and good storage stability.

The semiconductor element-forming composition contains:

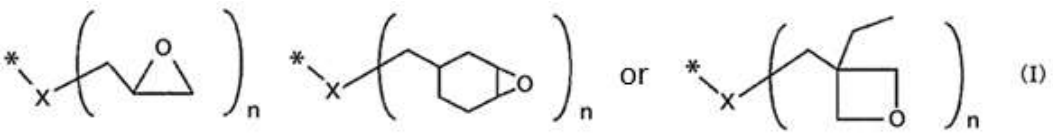
(A) a compound or polymer having a reactive group represented by a cyclic ether structure represented by the following Formula (I);

(B) a compound or polymer having a reactive group having reactivity with respect to the reactive group in (A);

(C) a basic curing agent;

(D) an acidic additive; and

(E) a solvent.



In Formula (I), * represents a bonding site; n represents 1 or 2; and when n = 1, X represents an ether bond, an ester bond, or an amide bond, and when n = 2, X represents a nitrogen atom or an amide bond.

[No figure]